



022704

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Paul A. Farrar  
Title: INTEGRATED CIRCUIT AND SEED LAYERS  
Attorney Docket No.: 303.673US3  
Customer No.: 21186

PATENT APPLICATION TRANSMITTAL

MAIL STOP PATENT APPLICATION

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items and information (as indicated with an "X"):

- ☒ Return postcard.
- ☒ **DIVISIONAL** of prior Patent Application No.(10/117041) (under 37 CFR 1.53(b)) comprising:
  - ☒ Specification (59 pgs, including claims numbered 1 through 79 and a 1 page Abstract).
  - ☒ Formal Drawing(s) (47 sheets).
  - ☒ Copy of signed Declaration (3 pgs)from prior application.
  - ☒ Copy of Power of Attorney from prior application (1 pgs).
  - ☒ Incorporation by Reference: *The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied herewith, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.*
  - ☒ Check in the amount of \$2692.00 to pay the filing fee.
- ☒ Prior application is assigned of record to Micron Technology, Inc..
- ☒ Information Disclosure Statement ( 2 pgs), Form 1449 ( 10 pgs )  
References NOT enclosed, cited in prior application.
- ☒ A Communication Concerning Related Applications (2 pgs.).

The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	79-20	59	x 18.00 =	\$1062.00
INDEPENDENT CLAIMS	13-3	10	x 86.00 =	\$860.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED				\$0.00
BASIC FEE				\$770.00
TOTAL				\$2692.00

Please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
Customer Number: 21186

By: David R. Cochran  
Atty: David R. Cochran  
Reg. No. 46,632

"Express Mail" mailing label number: EV415950039US  
Date of Deposit: February 27, 2004  
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17548 U.S. PTO  
10/789882  
022704

**S/N Unknown**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Paul A. Farrar	Examiner:	Unknown
Serial No.:	Unknown	Group Art Unit:	Unknown
Filed:	Herewith	Docket:	303.673US3
Title:	INTEGRATED CIRCUIT AND SEED LAYERS		

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**COMMUNICATION CONCERNING RELATED APPLICATION(S)**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/488098 6429120	January 18, 2000	303.618US1	METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
09/484303	January 18, 2000	303.648US1	METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
09/483869 6420262	January 18, 2000	303.664US1	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
09/483881	January 18, 2000	303.672US1	SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION
10/196078	July 16, 2002	303.664US2	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/196081	July 16, 2002	303.664US3	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/211855	August 1, 2002	303.618US2	METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: Unknown

Filing Date: Herewith

Title: INTEGRATED CIRCUIT AND SEED LAYERS

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10/195965	July 16, 2002	303.664US4	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/634274	August 5, 2003	1303.110US1	H2 Plasma Treatment
09/534224 6426289	March 24, 2000		
10/137293	May 3, 2002		

Respectfully submitted,

PAUL A. FARRAR


By Applicant's Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

Minneapolis, MN 55402

(612) 371-2157

Date 27 February 2004 By   
David R. Cochran  
Reg. No. 46,632

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